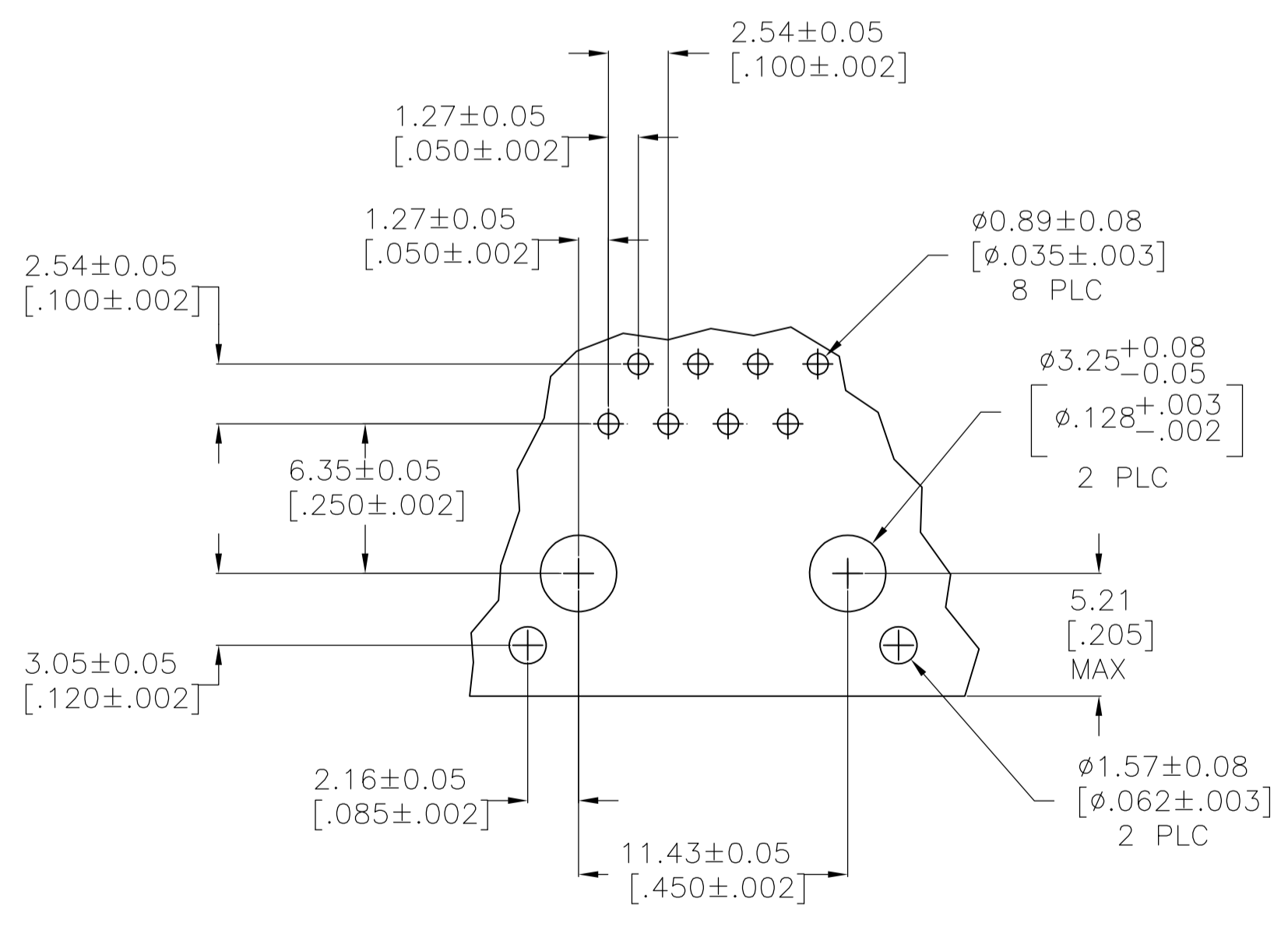
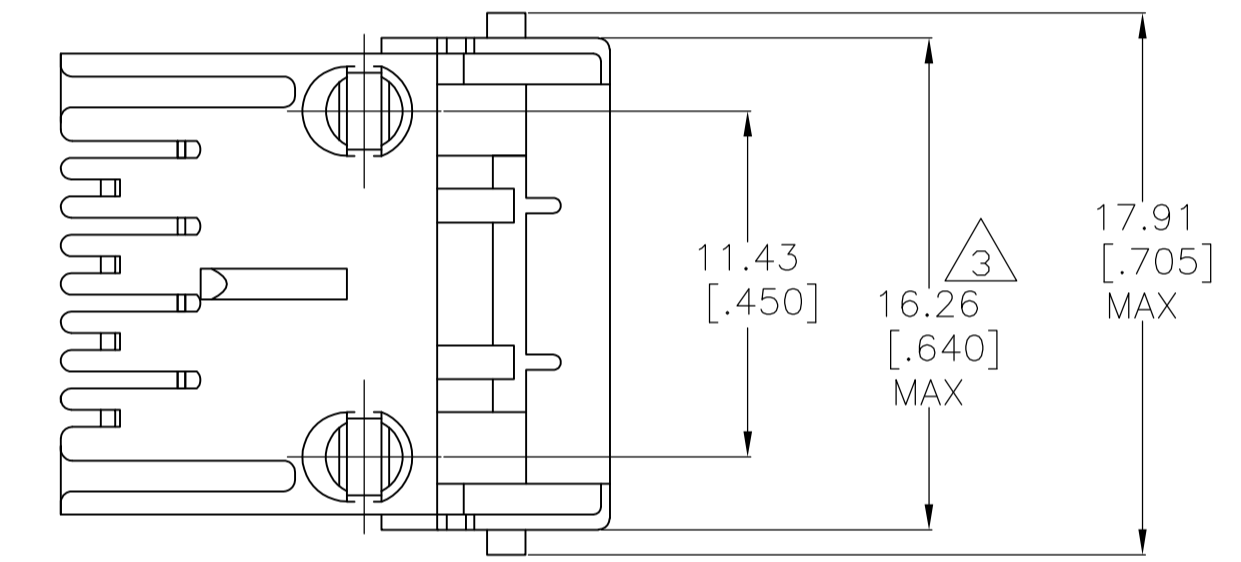
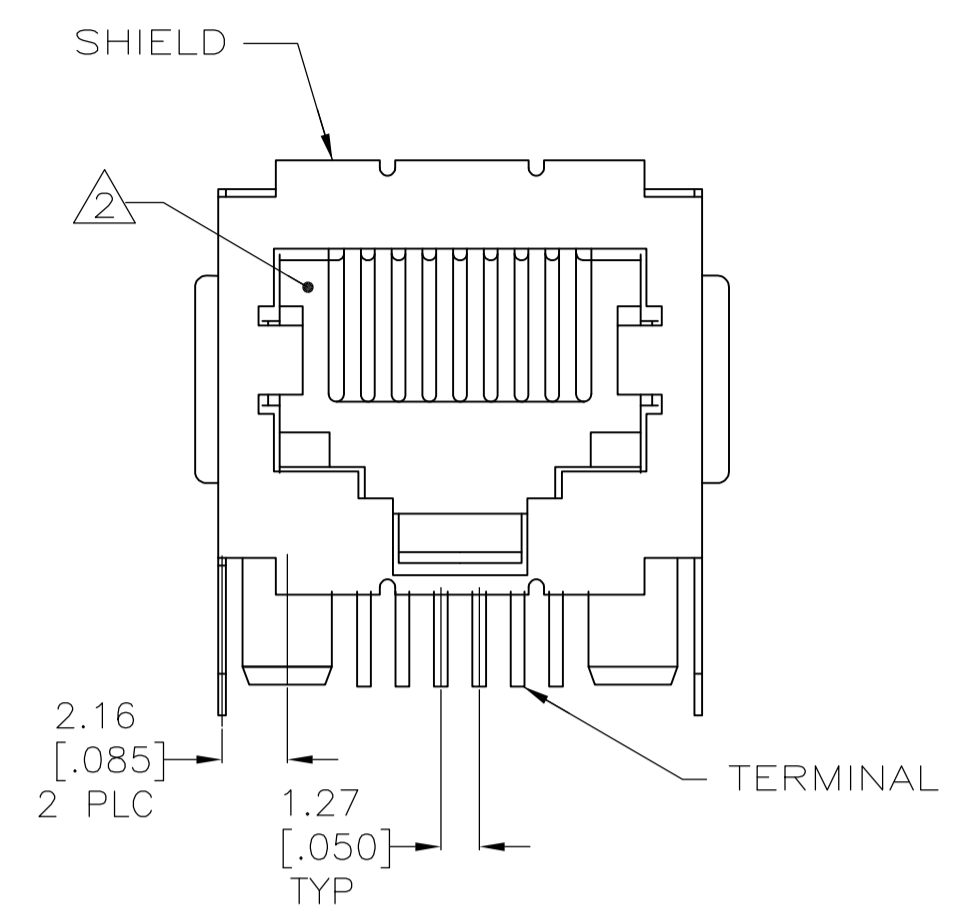
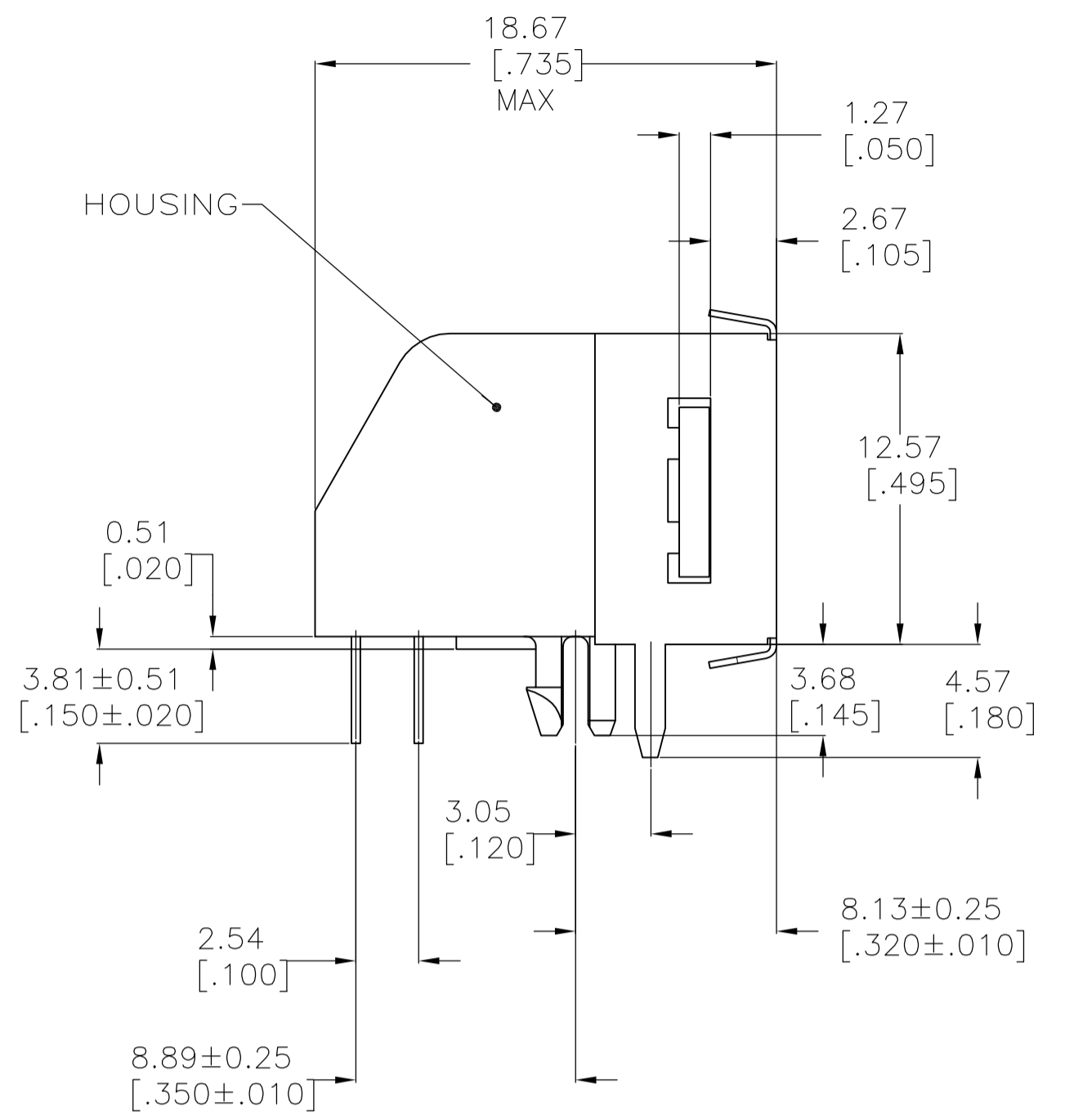
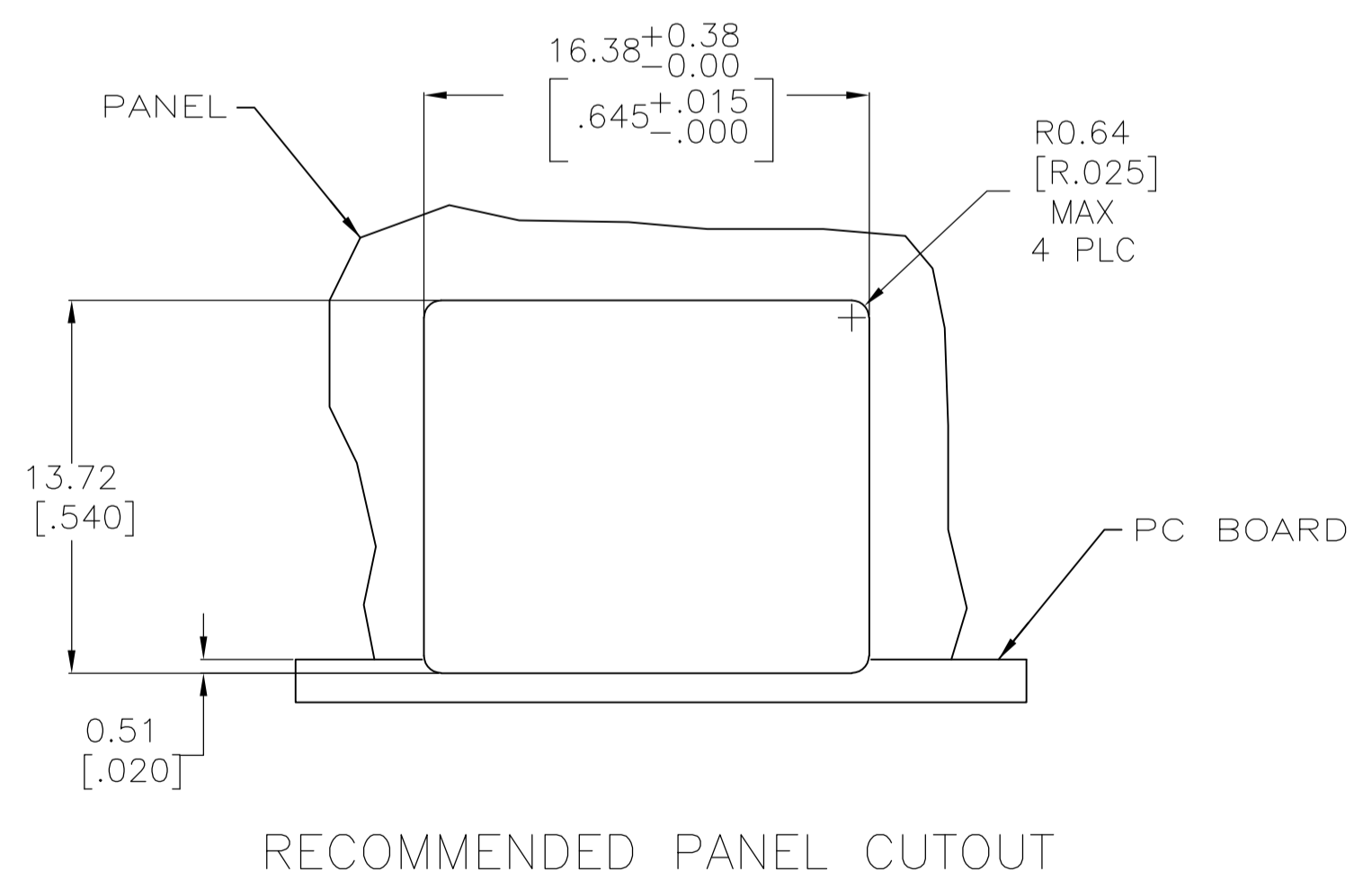


LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	CHK	APPV	
B1	REVISED PER ECO-11-005140		28MAR11	RK	HMR		



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

1. MATERIAL:  
 HOUSING (SEE TABLE) - COLOR: BLACK  
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE  
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0µm [.000120] MINIMUM THICK REFLOWED TIN
2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
3. DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE

YES	HIGH TEMP NYLON	5555141-3
NO	PBT POLYESTER	5555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN G GARRETT/L.A. MAYER 04APR2005	CHK J.WESTMAN 04APR2005	APVD S.FLICKINGER 04APR2005	NAME
0 PLC ± -	1 PLC ± -	2 PLC ± 0.13[.005]	3 PLC ± -	4 PLC ± -	ANGLES ± -
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT	SIZE A1	CAGE CODE 00779	DRAWING NO. 5555141
CUSTOMER DRAWING			SCALE 4:1	SHEET 1 OF 1	REV B1

**STE** TE Connectivity

MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS